

ABSTRACT OF THE DISCLOSURE

A conductive electroless plated powder includes core particles and a nickel film formed by an electroless plating process on the surface of each core particle, wherein crystal grain boundaries in the nickel film are primarily oriented in the direction of the thickness of the nickel film. An electroless gold plating film may be deposited on the nickel film as the top layer. The nickel film is formed by electroless plating using glycine or ethylenediamine as a complexing agent.